2020년 2월 13일(목), 10:45~12:00

Room F (스페이드 I, 6층)

B. Patterning 분과
[TF2-B] Patterning Technology: Photolithography and Etch

TF2-B-1 **10:45~11:00**	**Understanding the Exposure Process in the Extreme Ultra Violet Lithography** Sang-Kong Kim *Department of Science, Hongik University*
TF2-B-2 **11:00~11:30**	**[초청]** **TBA** 박종철 *삼성전자*
TF2-B-3 **11:30~11:45**	**SiO_2 Etching Using Hydrofluroethers: The Use of Low Global Warming Potential Materials for Plasma Etching** Jun-Hyun Kim[1] and Chang-Koo Kim[2] *[1]Institute of NT-IT Fusion Technology, Ajou University, [2]Department of Chemical Engineering and Department of Energy Systems Research, Ajou University*
TF2-B-4 **11:45~12:00**	**Influence of Pulse-modulated RF Source Plasma on Etch Characteristic of Nanoscale Patterned Copper Thin Film Using CH_3COOH/Ar** Eun Taek Lim, Moon Hwan Cha, and Chee Won Chung *Department of Chemical Engineering, Inha University*